

IN THE CLAIMS

1. (Original) A method of mounting a planar electronic circuit chip on a flexible sheet together with another planer electric element, characterized by steps of:

selecting the another electric element and the electronic circuit chip so that the planar surface of the another electric element is greater than the planar surface of the electronic circuit chip; and

mounting the another electric element and the electronic circuit chip onto the sheet so that the planer surface of the another electronic element and the planar surface of the electronic circuit chip are located in parallel with the surface of the sheet, and the planer surface of the electronic circuit chip is accommodated within the planar surface of the another electric element as viewed in a direction perpendicular to the surface of the sheet.

Claims 2-14 (Canceled)